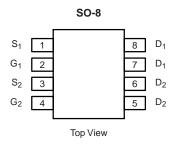


APM4927KC-TRL-VB Datasheet Dual P-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^{d, e}	Q _g (Typ.)		
- 30	0.021 at V _{GS} = - 10 V	- 8.0	15 nC		
- 30	0.028 at V _{GS} = - 4.5 V	- 7.0	10110		



FEATURES

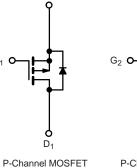
- Halogen-free
- Trench Power MOSFET ٠
- 100 % UIS Tested

APPLICATIONS

- Load Switches
 - Notebook PCs
 - Desktop PCs
 - Game Stations

G₁





 S_1

 D_2 P-Channel MOSFET

 S_2

C

Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V _{DS}	- 30	V		
Gate-Source Voltage		V _{GS}	± 20	V	
	T _C = 25 °C		- 9.5 ^e		
Continuous Drain Current ($T_J = 150 \ ^{\circ}C$)	T _C = 70 °C		- 8.0 ^e		
$Continuous Drain Current (T_j = 150 C)$	T _A = 25 °C	I _D	- 8.3 ^{a, b}		
	T _A = 70 °C		- 7.9 ^{a, b}	A	
Pulsed Drain Current		I _{DM}	- 32 ^e	A	
Continuous Course Durie Diade Current	T _C = 25 °C		- 4.1		
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	- 2.0 ^{a, b}		
Avalanche Current	1 0.1 mll	I _{AS}	- 20		
Single-Pulse Avalanche Energy	L = 0.1 mH	E _{AS}	20	mJ	
	T _C = 25 °C		5.0		
Mauianum Danna Diasia atian	T _C = 70 °C		3.2	14/	
Maximum Power Dissipation	T _A = 25 °C	P _D	2.5 ^{a, b}	W	
	T _A = 70 °C	1	1.6 ^{a, b}		
Operating Junction and Storage Temperature Range	T _J , T _{stq}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient ^{a, c}	t ≤ 10 s	R _{thJA}	38	50	°C/W	
Maximum Junction-to-Foot	Steady State	R _{thJF}	20	25	-C/W	

Notes:

a. Surface mounted on 1" x 1" FR4 board.

b. t = 10 s.

c. Maximum under Steady State conditions is 85 °C/W.

d. Based on T_C = 25 °C.

e. Limited by package.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static	-					
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = - 250 μA	- 30			V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$			- 31		mV/°C
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = - 250 μA		4.5		
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \ \mu A$	- 1.0		- 3.0	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}$ $V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 55 \text{ °C}$			- 1 - 5	μA
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge$ - 10 V, V_{GS} = - 10 V	- 30			A
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = -10 \text{ V}, \text{ I}_{D} = -7.3 \text{ A}$ $V_{GS} = -4.5 \text{ V}, \text{ I}_{D} = -6.2 \text{ A}$		0.021		Ω
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 10 V, I _D = - 9.1 A		23		S
Dynamic ^b	0.0			I		I
Input Capacitance	C _{iss}			1350		
Output Capacitance	C _{oss}	V _{DS} = - 15 V, V _{GS} = 0 V, f = 1 MHz		215		pF
Reverse Transfer Capacitance	C _{rss}			185		
Total Gate Charge	Qg	V _{DS} = - 15 V, V _{GS} = - 10 V, I _D = - 9.1 A		32	50	
Gate-Source Charge	Q _{gs}	V _{DS} = - 15 V, V _{GS} = - 4.5 V, I _D = - 9.1 A		15 4	25	nC
Gate-Drain Charge	Q _{gs} Q _{gd}	$V_{\rm DS} = -10$ V, $V_{\rm GS} = -4.0$ V, $I_{\rm D} = -0.1$ A		7.5		
Gate Resistance	R _g	f = 1 MHz		5.8		Ω
Turn-On Delay Time	t _{d(on)}			10	15	52
Rise Time	t _r	V _{DD} = - 15 V, R _I = 15 Ω		8	15	-
Turn-Off DelayTime	t _{d(off)}	$I_D \cong -1 \text{ A}, \text{ V}_{\text{GEN}} = -10 \text{ V}, \text{ R}_{\text{g}} = 1 \Omega$		45	70	
Fall Time	t _f			12	25	
Turn-On Delay Time	t _{d(on)}			42	70	ns
Rise Time	t _r	$V_{DD} = -15 \text{ V}, \text{ R}_{1} = 15 \Omega$		35	60	-
Turn-Off DelayTime	t _{d(off)}	$I_D \cong$ - 1 Å, V_{GEN} = - 4.5 V, R_q = 1 Ω		40	70	
Fall Time	t _f			16	30	
Drain-Source Body Diode Characterist	ics					1
Continous Source-Drain Diode Current	۱ _s	T _C = 25 °C			- 4.1	
Pulse Diode Forward Current	I _{SM}	-			- 32	A
Body Diode Voltage	V _{SD}	I _S = - 2 A, V _{GS} = 0 V		- 0.75	- 1.2	V
Body Diode Reverse Recovery Time	t _{rr}			34	60	ns
Body Diode Reverse Recovery Charge	Q _{rr}			22	40	nC
Reverse Recovery Fall Time	t _a	$I_{F} = -2 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_{J} = 25 \text{ °C}$		11		
Reverse Recovery Rise Time	t _b			23		ns

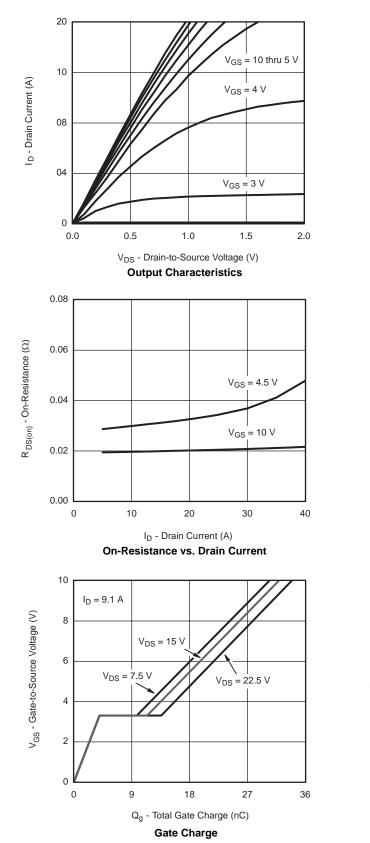
Notes:

a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

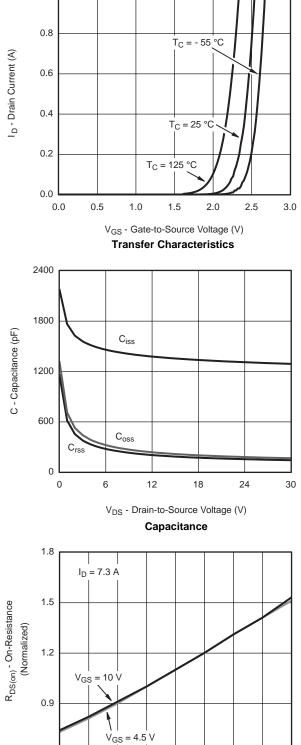
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.





TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



1.0

T_J - Junction Temperature (°C) On-Resistance vs. Junction Temperature

50

75

100

125

0.6

- 50

- 25

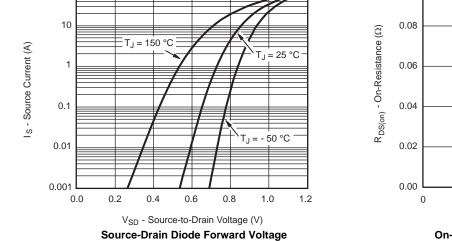
0

25

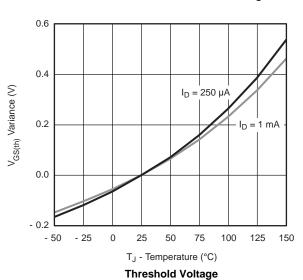
150

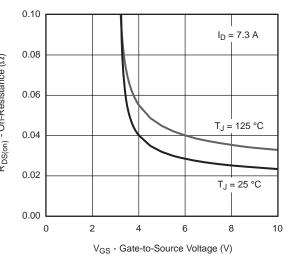
100



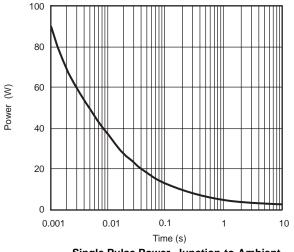


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

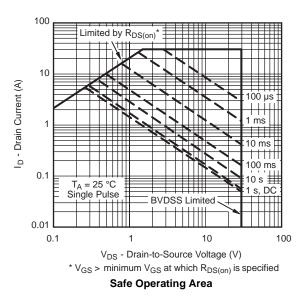




On-Resistance vs. Gate-to-Source Voltage

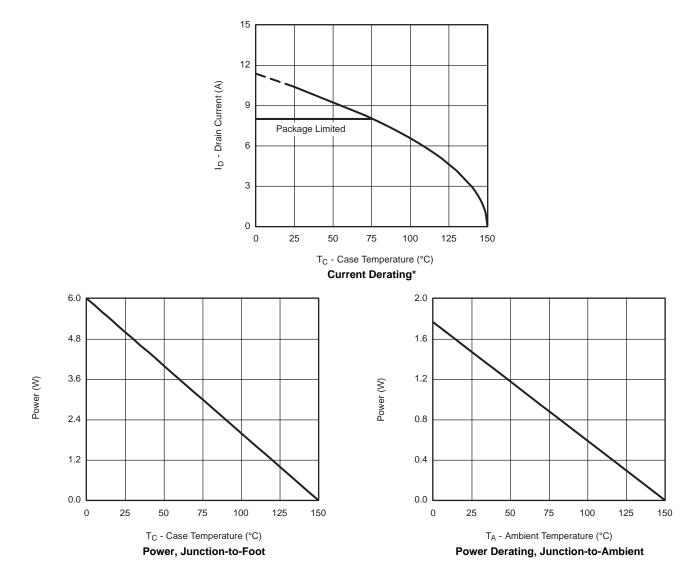


Single Pulse Power, Junction-to-Ambient





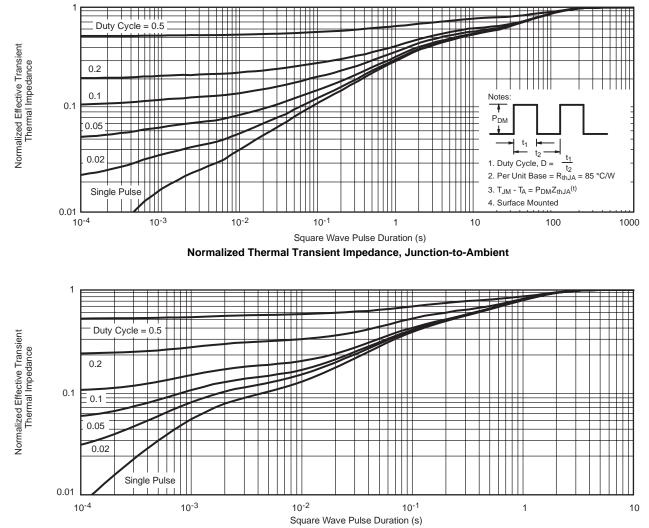
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



* The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



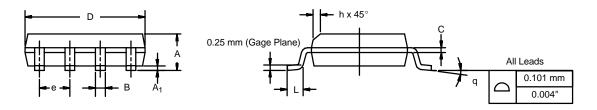
Normalized Thermal Transient Impedance, Junction-to-Foot



SOIC (NARROW): 8-LEAD

JEDEC Part Number: MS-012

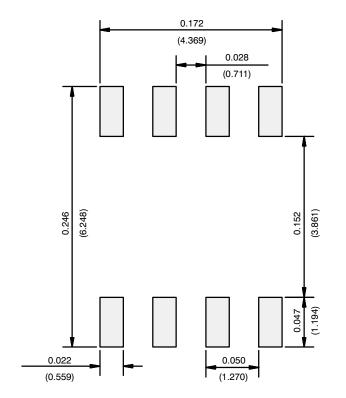




	MILLIM	IETERS	INCHES		
DIM	Min	Мах	Min	Max	
A	1.35	1.75	0.053	0.069	
A ₁	0.10	0.20	0.004	0.008	
В	0.35	0.51	0.014	0.020	
С	0.19	0.25	0.0075	0.010	
D	4.80	5.00	0.189	0.196	
E	3.80	4.00	0.150	0.157	
е	1.27 BSC		0.050 BSC		
Н	5.80	6.20	0.228	0.244	
h	0.25	0.50	0.010	0.020	
L	0.50	0.93	0.020	0.037	
q	0°	8°	0°	8°	
S	0.44	0.64	0.018	0.026	
ECN: C-06527-Rev. I, 11-Sep-06 DWG: 5498					



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)



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